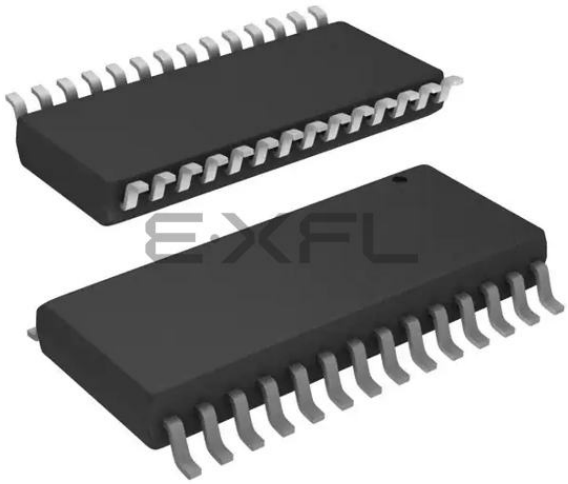

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	25MHz
Connectivity	CANbus, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2480-e-so

3.0 OSCILLATOR CONFIGURATIONS

3.1 Oscillator Types

PIC18F2480/2580/4480/4580 devices can be operated in ten different oscillator modes. The user can program the Configuration bits, FOSC<3:0>, in Configuration Register 1H to select one of these ten modes:

1. LP Low-Power Crystal
2. XT Crystal/Resonator
3. HS High-Speed Crystal/Resonator
4. HSPLL High-Speed Crystal/Resonator with PLL Enabled
5. RC External Resistor/Capacitor with FOSC/4 Output on RA6
6. RCIO External Resistor/Capacitor with I/O on RA6
7. INTIO1 Internal Oscillator with FOSC/4 Output on RA6 and I/O on RA7
8. INTIO2 Internal Oscillator with I/O on RA6 and RA7
9. EC External Clock with FOSC/4 Output
10. ECIO External Clock with I/O on RA6

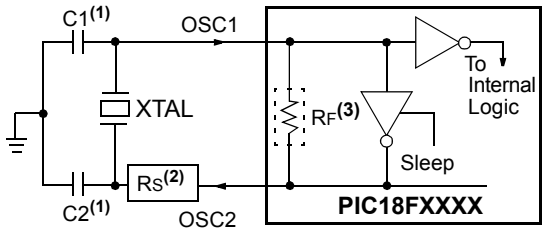
3.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HSPLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 3-1 shows the pin connections.

The oscillator design requires the use of a parallel resonant crystal.

Note: Use of a series resonant crystal may give a frequency out of the crystal manufacturer's specifications.

FIGURE 3-1: CRYSTAL/CERAMIC RESONATOR OPERATION (XT, LP, HS OR HSPLL CONFIGURATION)



Note 1: See Table 3-1 and Table 3-2 for initial values of C1 and C2.
2: A series resistor (RS) may be required for AT strip cut crystals.
3: RF varies with the oscillator mode chosen.

TABLE 3-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Typical Capacitor Values Used:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	56 pF 47 pF 33 pF	56 pF 47 pF 33 pF
HS	8.0 MHz 16.0 MHz	27 pF 22 pF	27 pF 22 pF

Capacitor values are for design guidance only.

These capacitors were tested with the resonators listed below for basic start-up and operation. **These values are not optimized**.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes on page 30 for additional information.

Resonators Used:	
455 kHz	4.0 MHz
2.0 MHz	8.0 MHz
16.0 MHz	

Note: When using resonators with frequencies above 3.5 MHz, the use of HS mode, rather than XT mode, is recommended. HS mode may be used at any VDD for which the controller is rated. If HS is selected, it is possible that the gain of the oscillator will overdrive the resonator. Therefore, a series resistor should be placed between the OSC2 pin and the resonator. As a good starting point, the recommended value of RS is 330Ω.

REGISTER 3-1: OSCTUNE: OSCILLATOR TUNING REGISTER

R/W-0	R/W-0(1)	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTSRC	PLLEN(1)	—	TUN4	TUN3	TUN2	TUN1	TUN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **INTSRC:** Internal Oscillator Low-Frequency Source Select bit
1 = 31.25 kHz device clock derived from 8 MHz INTOSC source (divide-by-256 enabled)
0 = 31 kHz device clock derived directly from INTRC internal oscillator

bit 6 **PLLEN:** Frequency Multiplier PLL for INTOSC Enable bit(1)
1 = PLL enabled for INTOSC (4 MHz and 8 MHz only)
0 = PLL disabled

bit 5 **Unimplemented:** Read as '0'

bit 4-0 **TUN<4:0>:** Frequency Tuning bits
01111 = Maximum frequency
• •
• •
00001
00000 = Center frequency. Oscillator module is running at the calibrated frequency.
11111
• •
• •
10000 = Minimum frequency

Note 1: Available only in certain oscillator configurations; otherwise, this bit is unavailable and reads as '0'. See text for details.

3.6.5.1 Compensating with the EUSART

An adjustment may be required when the EUSART begins to generate framing errors or receives data with errors while in Asynchronous mode. Framing errors indicate that the device clock frequency is too high. To adjust for this, decrement the value in OSCTUNE to reduce the clock frequency. On the other hand, errors in data may suggest that the clock speed is too low. To compensate, increment OSCTUNE to increase the clock frequency.

3.6.5.2 Compensating with the Timers

This technique compares device clock speed to some reference clock. Two timers may be used; one timer is clocked by the peripheral clock, while the other is clocked by a fixed reference source, such as the Timer1 oscillator.

Both timers are cleared, but the timer clocked by the reference generates interrupts. When an interrupt occurs, the internally clocked timer is read and both timers are cleared. If the internally clocked timer value is greater than expected, then the internal oscillator block is running too fast. To adjust for this, decrement the OSCTUNE register.

3.6.5.3 Compensating with the CCP Module in Capture Mode

A CCP module can use free-running Timer1 (or Timer3), clocked by the internal oscillator block and an external event with a known period (i.e., AC power frequency). The time of the first event is captured in the CCPRxH:CCPRxL registers and is recorded for use later. When the second event causes a capture, the time of the first event is subtracted from the time of the second event. Since the period of the external event is known, the time difference between events can be calculated.

If the measured time is much greater than the calculated time, the internal oscillator block is running too fast. To compensate, decrement the OSCTUNE register. If the measured time is much less than the calculated time, the internal oscillator block is running too slow. To compensate, increment the OSCTUNE register.

4.3 Sleep Mode

The power-managed Sleep mode in the PIC18F2480/2580/4480/4580 devices is identical to the legacy Sleep mode offered in all other PIC devices. It is entered by clearing the IDLEN bit (the default state on device Reset) and executing the SLEEP instruction. This shuts down the selected oscillator (Figure 4-5). All clock source status bits are cleared.

Entering the Sleep mode from any other mode does not require a clock switch. This is because no clocks are needed once the controller has entered Sleep. If the WDT is selected, the INTRC source will continue to operate. If the Timer1 oscillator is enabled, it will also continue to run.

When a wake event occurs in Sleep mode (by interrupt, Reset or WDT time-out), the device will not be clocked until the clock source selected by the SCS1:SCS0 bits becomes ready (see Figure 4-6), or it will be clocked from the internal oscillator block if either the Two-Speed Start-up or the Fail-Safe Clock Monitor are enabled (see **Section 25.0 "Special Features of the CPU"**). In either case, the OSTS bit is set when the primary clock is providing the device clocks. The IDLEN and SCS bits are not affected by the wake-up.

4.4 Idle Modes

The Idle modes allow the controller's CPU to be selectively shut down while the peripherals continue to operate. Selecting a particular Idle mode allows users to further manage power consumption.

If the IDLEN bit is set to '1' when a SLEEP instruction is executed, the peripherals will be clocked from the clock source selected using the SCS<1:0> bits; however, the CPU will not be clocked. The clock source status bits are not affected. Setting IDLEN and executing a SLEEP instruction provides a quick method of switching from a given Run mode to its corresponding Idle mode.

If the WDT is selected, the INTRC source will continue to operate. If the Timer1 oscillator is enabled, it will also continue to run.

Since the CPU is not executing instructions, the only exits from any of the Idle modes are by interrupt, WDT time-out or a Reset. When a wake event occurs, CPU execution is delayed by an interval of TCSD (parameter 38, Table 28-10) while it becomes ready to execute code. When the CPU begins executing code, it resumes with the same clock source for the current Idle mode. For example, when waking from RC_IDLE mode, the internal oscillator block will clock the CPU and peripherals (in other words, RC_RUN mode). The IDLEN and SCS bits are not affected by the wake-up.

While in any Idle mode or Sleep mode, a WDT time-out will result in a WDT wake-up to the Run mode currently specified by the SCS<1:0> bits.

FIGURE 4-5: TRANSITION TIMING FOR ENTRY TO SLEEP MODE

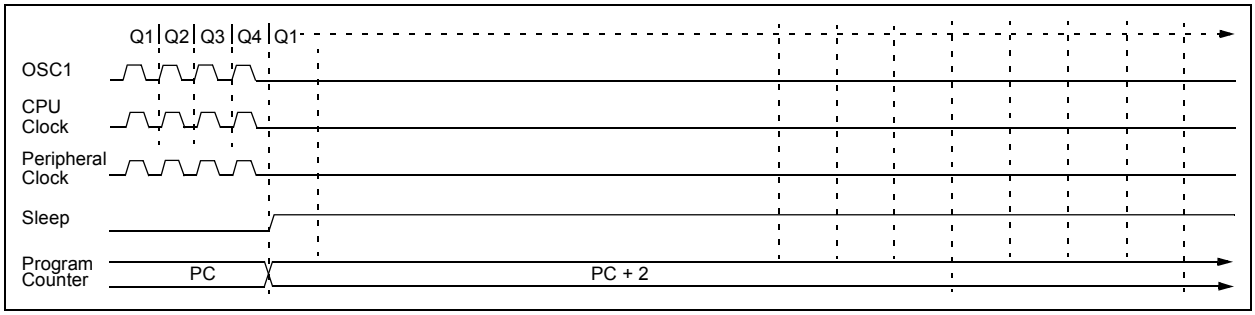
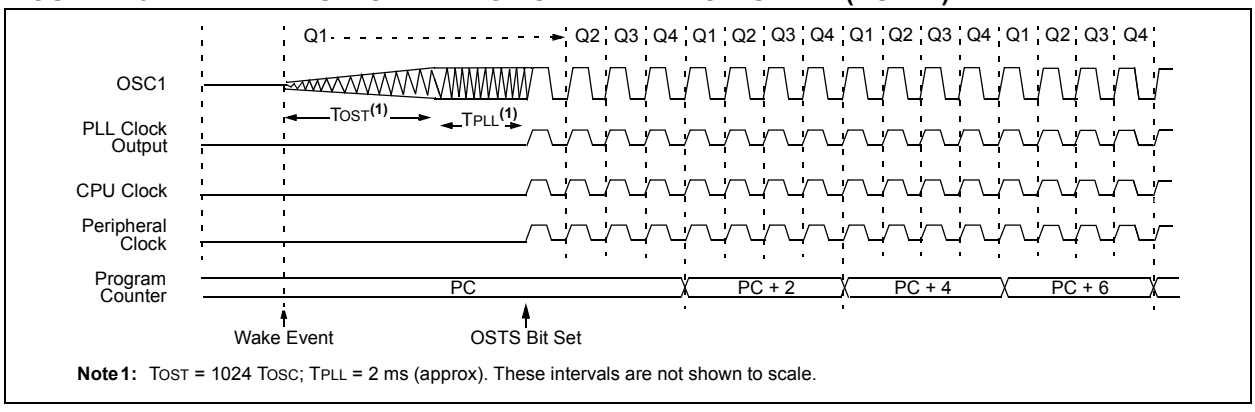


FIGURE 4-6: TRANSITION TIMING FOR WAKE FROM SLEEP (HSPLL)



Note 1: TOST = 1024 TOSC; TPLL = 2 ms (approx). These intervals are not shown to scale.

TABLE 5-4: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices				Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets, WDT Reset, RESET Instruction, Stack Resets	Wake-up via WDT or Interrupt
PIR2	2480	2580	4480	4580	00-0 0000	00-0 0000	uu-u uuuu(1)
	2480	2580	4480	4580	0--0 000-	0--0 000-	u--u uuu-(1)
PIE2	2480	2580	4480	4580	00-0 0000	00-0 0000	uu-u uuuu
	2480	2580	4480	4580	0--0 000-	0--0 000-	u--u uuu-
IPR1	2480	2580	4480	4580	1111 1111	1111 1111	uuuu uuuu
	2480	2580	4480	4580	-111 1111	-111 1111	-uuu uuuu
PIR1	2480	2580	4480	4580	0000 0000	0000 0000	uuuu uuuu(1)
	2480	2580	4480	4580	-000 0000	-000 0000	-uuu uuuu
PIE1	2480	2580	4480	4580	0000 0000	0000 0000	uuuu uuuu
	2480	2580	4480	4580	-000 0000	-000 0000	-uuu uuuu
OSCTUNE	2480	2580	4480	4580	--00 0000	--00 0000	--uu uuuu
TRISE	2480	2580	4480	4580	0000 -111	0000 -111	uuuu -uuu
TRISD	2480	2580	4480	4580	1111 1111	1111 1111	uuuu uuuu
TRISC	2480	2580	4480	4580	1111 1111	1111 1111	uuuu uuuu
TRISB	2480	2580	4480	4580	1111 1111	1111 1111	uuuu uuuu
TRISA(5)	2480	2580	4480	4580	1111 1111(5)	1111 1111(5)	uuuu uuuu(5)
LATE	2480	2580	4480	4580	---- -xxx	---- -uuu	---- -uuu
LATD	2480	2580	4480	4580	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATC	2480	2580	4480	4580	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATB	2480	2580	4480	4580	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATA(5)	2480	2580	4480	4580	xxxx xxxx(5)	uuuu uuuu(5)	uuuu uuuu(5)
PORTE	2480	2580	4480	4580	---- x000	---- x000	---- uuuu
PORTD	2480	2580	4480	4580	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	2480	2580	4480	4580	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTB	2480	2580	4480	4580	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA(5)	2480	2580	4480	4580	xx0x 0000(5)	uu0u 0000(5)	uuuu uuuu(5)
ECANCON	2480	2580	4480	4580	0001 0000	0001 0000	uuuu uuuu
TXERRCNT	2480	2580	4480	4580	0000 0000	0000 0000	uuuu uuuu
RXERRCNT	2480	2580	4480	4580	0000 0000	0000 0000	uuuu uuuu
COMSTAT	2480	2580	4480	4580	0000 0000	0000 0000	uuuu uuuu
CIOCON	2480	2580	4480	4580	--00 ----	--00 ----	--uu ----

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

Note 1: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

4: See Table 5-3 for Reset value for specific condition.

5: Bits 6 and 7 of PORTA, LATA and TRISA are enabled, depending on the oscillator mode selected. When not enabled as PORTA pins, they are disabled and read '0'.

6: This register reads all '0's until ECAN™ technology is set up in Mode 1 or Mode 2.

TABLE 6-1: SPECIAL FUNCTION REGISTER MAP FOR PIC18F2480/2580/4480/4580 DEVICES (CONTINUED)

Address	Name
D7Fh	—
D7Eh	—
D7Dh	—
D7Ch	—
D7Bh	RXF11EIDL
D7Ah	RXF11EIDH
D79h	RXF11SIDL
D78h	RXF11SIDH
D77h	RXF10EIDL
D76h	RXF10EIDH
D75h	RXF10SIDL
D74h	RXF10SIDH
D73h	RXF9EIDL
D72h	RXF9EIDH
D71h	RXF9SIDL
D70h	RXF9SIDH
D6Fh	—
D6Eh	—
D6Dh	—
D6Ch	—
D6Bh	RXF8EIDL
D6Ah	RXF8EIDH
D69h	RXF8SIDL
D68h	RXF8SIDH
D67h	RXF7EIDL
D66h	RXF7EIDH
D65h	RXF7SIDL
D64h	RXF7SIDH
D63h	RXF6EIDL
D62h	RXF6EIDH
D61h	RXF6SIDL
D60h	RXF6SIDH

Note 1: Registers available only on PIC18F4X80 devices; otherwise, the registers read as '0'.
2: When any TX_ENn bit in RX_TX_SELn is set, then the corresponding bit in this register has transmit properties.
3: This is not a physical register.

7.5 Writing to Flash Program Memory

The minimum programming block is 16 words or 32 bytes. Word or byte programming is not supported.

Table writes are used internally to load the holding registers needed to program the Flash memory. There are 32 holding registers used by the table writes for programming.

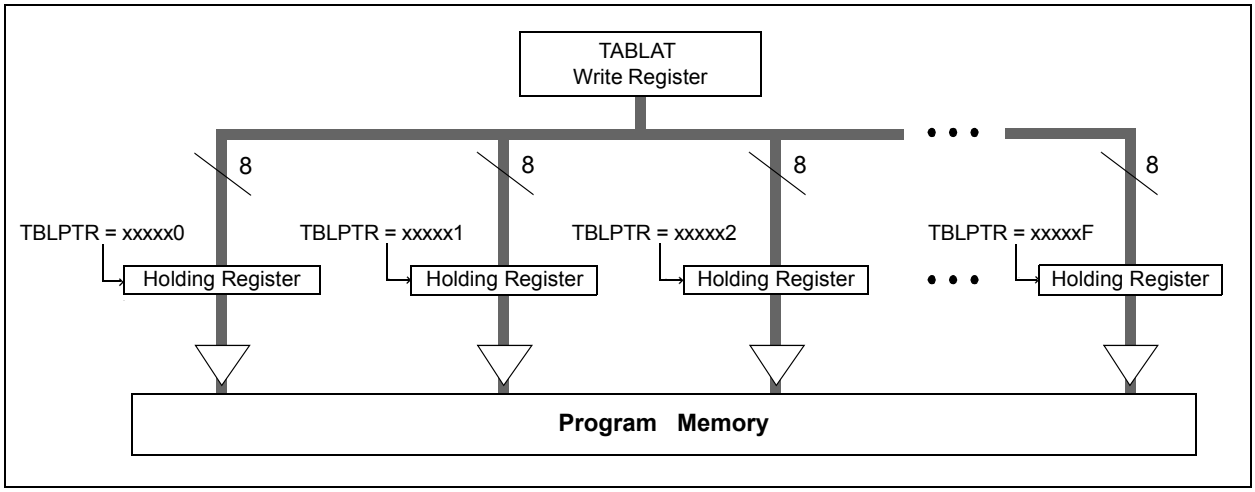
Since the Table Latch (TABLAT) is only a single byte, the TBLWT instruction may need to be executed 32 times for each programming operation. All of the table write operations will essentially be short writes because only the holding registers are written. At the end of updating the 32 holding registers, the EECON1 register must be written to in order to start the programming operation with a long write.

The long write is necessary for programming the internal Flash. Instruction execution is halted while in a long write cycle. The long write will be terminated by the internal programming timer.

The EEPROM on-chip timer controls the write time. The write/erase voltages are generated by an on-chip charge pump, rated to operate over the voltage range of the device.

Note:	The default value of the holding registers on device Resets and after write operations is FFh. A write of FFh to a holding register does not modify that byte. This means that individual bytes of program memory may be modified, provided that the change does not attempt to change any bit from a '0' to a '1'. When modifying individual bytes, it is not necessary to load all 32 holding registers before executing a write operation.

FIGURE 7-5: TABLE WRITES TO FLASH PROGRAM MEMORY



7.5.1 FLASH PROGRAM MEMORY WRITE SEQUENCE

The sequence of events for programming an internal program memory location should be:

1. Read 64 bytes into RAM.
2. Update data values in RAM as necessary.
3. Load Table Pointer register with address being erased.
4. Execute the row erase procedure.
5. Load Table Pointer register with address of first byte being written.
6. Write the 32 bytes into the holding registers with auto-increment.
7. Set the EECON1 register for the write operation:
   - set EEPGD bit to point to program memory;
   - clear the CFGS bit to access program memory;
   - set WREN to enable byte writes.
8. Disable interrupts.
9. Write 55h to EECON2.
10. Write 0AAh to EECON2.
11. Set the WR bit. This will begin the write cycle.
12. The CPU will stall for duration of the write (about 2 ms using internal timer). After writing to the holding registers, it will be set to 0xFF.
13. Repeat the question three more times.
14. Re-enable interrupts.
15. Verify the memory (table read).

This procedure will require about 6 ms to update one row of 64 bytes of memory. An example of the required code is given in Example 7-3.

Note:	Before setting the WR bit, the Table Pointer address needs to be within the intended address range of the 32 bytes in the holding register.

12.1 Timer0 Operation

Timer0 can operate as either a timer or a counter; the mode is selected by clearing the T0CS bit (T0CON<5>). In Timer mode, the module increments on every clock by default unless a different prescaler value is selected (see **Section 12.3 "Prescaler"**). If the TMR0 register is written to, the increment is inhibited for the following two instruction cycles. The user can work around this by writing an adjusted value to the TMR0 register.

The Counter mode is selected by setting the T0CS bit (= 1). In Counter mode, Timer0 increments either on every rising or falling edge of pin, RA4/T0CKI. The incrementing edge is determined by the Timer0 Source Edge Select bit, T0SE (T0CON<4>); clearing this bit selects the rising edge. Restrictions on the external clock input are discussed below.

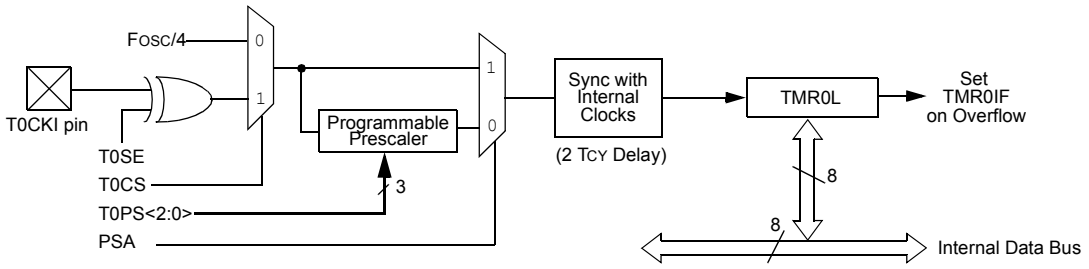
An external clock source can be used to drive Timer0; however, it must meet certain requirements to ensure that the external clock can be synchronized with the internal phase clock (TOSC). There is a delay between synchronization and the onset of incrementing the timer/counter.

12.2 Timer0 Reads and Writes in 16-Bit Mode

TMR0H is not the actual high byte of Timer0 in 16-bit mode; it is actually a buffered version of the real high byte of Timer0, which is not directly readable nor writable (refer to Figure 12-2). TMR0H is updated with the contents of the high byte of Timer0 during a read of TMR0L. This provides the ability to read all 16 bits of Timer0 without having to verify that the read of the high and low byte were valid, due to a rollover between successive reads of the high and low byte.

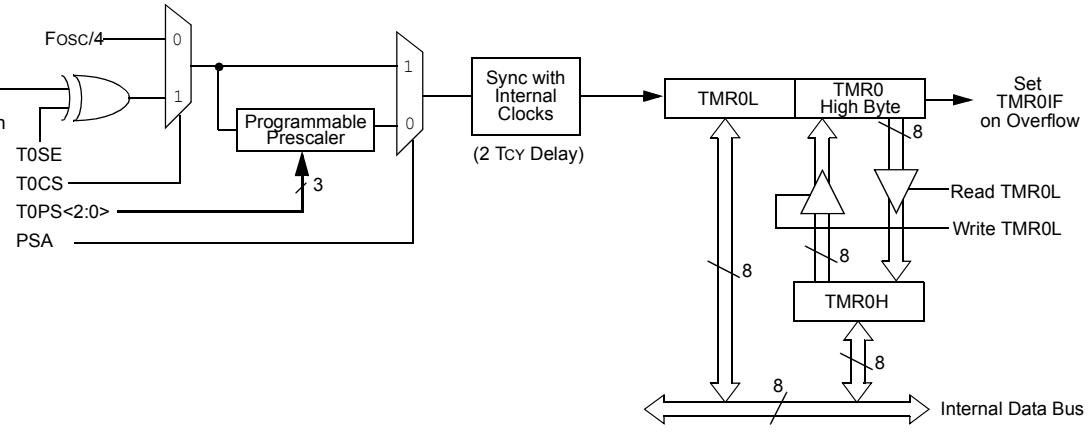
Similarly, a write to the high byte of Timer0 must also take place through the TMR0H Buffer register. The high byte is updated with the contents of TMR0H when a write occurs to TMR0L. This allows all 16 bits of Timer0 to be updated at once.

FIGURE 12-1: TIMER0 BLOCK DIAGRAM (8-BIT MODE)



Note: Upon Reset, Timer0 is enabled in 8-bit mode with clock input from T0CKI max. prescale.

FIGURE 12-2: TIMER0 BLOCK DIAGRAM (16-BIT MODE)



Note: Upon Reset, Timer0 is enabled in 8-bit mode with clock input from T0CKI max. prescale.

TABLE 16-3: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, TIMER1 AND TIMER3

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	55
RCON	IPEN	SBOREN(3)	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	56
IPR1	PSPIP	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	58
PIR1	PSPIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	58
PIE1	PSPIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	58
IPR2	OSCFIP	CMIP(2)	—	EEIP	BCLIP	HLVDIP	TMR3IP	ECCP1IP(2)	58
PIR2	OSCFIF	CMIF(2)	—	EEIF	BCLIF	HLVDIF	TMR3IF	ECCP1IF(2)	58
PIE2	OSCFIE	CMIE(2)	—	EEIE	BCLIE	HLVDIE	TMR3IE	ECCP1IE(2)	57
TRISB	PORTB Data Direction Register								58
TRISC	PORTC Data Direction Register								58
TMR1L	Timer1 Register Low Byte								56
TMR1H	Timer1 Register High Byte								56
T1CON	RD16	T1RUN	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	56
TMR3H	Timer3 Register High Byte								57
TMR3L	Timer3 Register Low Byte								57
T3CON	RD16	T3ECCP1(1)	T3CKPS1	T3CKPS0	T3CCP1(1)	$\overline{T3SYNC}$	TMR3CS	TMR3ON	57
CCPR1L	Capture/Compare/PWM Register 1 Low Byte								57
CCPR1H	Capture/Compare/PWM Register 1 High Byte								57
CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	57
ECCPR1L(1)	Enhanced Capture/Compare/PWM Register 1 Low Byte								57
ECCPR1H(1)	Enhanced Capture/Compare/PWM Register 1 High Byte								57
ECCP1CON(1)	EPWM1M1	EPWM1M0	EDC1B1	EDC1B0	ECCP1M3	ECCP1M2	ECCP1M1	ECCP1M0	57

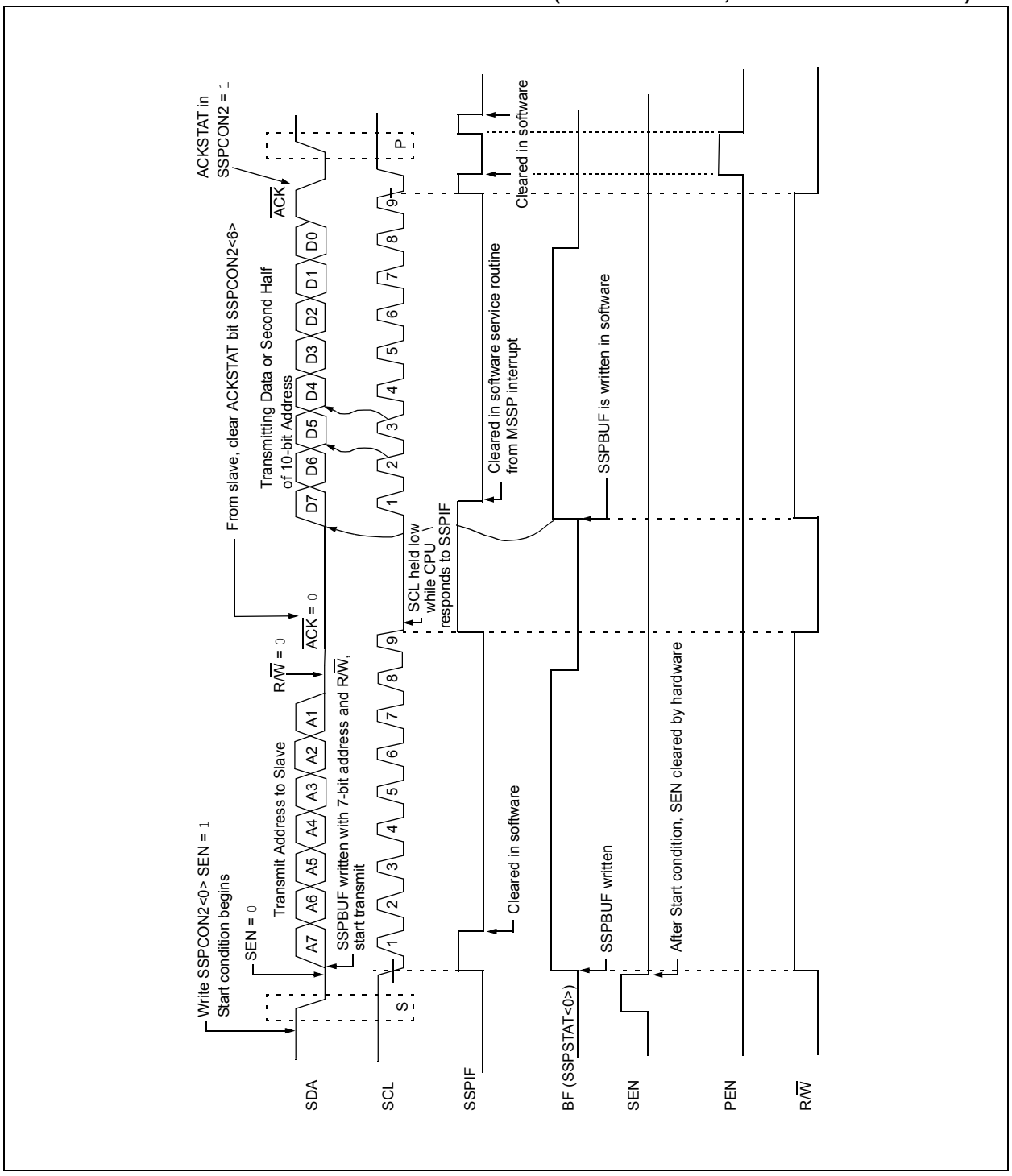
Legend: — = unimplemented, read as '0'. Shaded cells are not used by capture, compare, Timer1 or Timer3.

Note 1: These bits or registers are available on PIC18F4X80 devices only.

2: These bits are available on PIC18F4X80 devices and reserved on PIC18F2X80 devices.

3: The SBOREN bit is only available when CONFIG2L<1:0> = 01; otherwise, it is disabled and reads as '0'. See **Section 5.4 "Brown-out Reset (BOR)"**.

FIGURE 18-21: I²C™ MASTER MODE WAVEFORM (TRANSMISSION, 7 OR 10-BIT ADDRESS)



21.0 COMPARATOR MODULE

The analog comparator module contains two comparators that can be configured in a variety of ways. The inputs can be selected from the analog inputs multiplexed with pins, RA0 through RA5, as well as the on-chip voltage reference (see **Section 22.0 "Comparator Voltage Reference Module"**). The digital outputs (normal or inverted) are available at the pin level and can also be read through the control register.

The CMCON register (Register 21-1) selects the comparator input and output configuration. Block diagrams of the various comparator configurations are shown in Figure 21-1.

REGISTER 21-1: CMCON: COMPARATOR CONTROL REGISTER

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **C2OUT**: Comparator 2 Output bit
When C2INV = 0:
1 = C2 VIN+ > C2 VIN-
0 = C2 VIN+ < C2 VIN-
When C2INV = 1:
1 = C2 VIN+ < C2 VIN-
0 = C2 VIN+ > C2 VIN-

bit 6 **C1OUT**: Comparator 1 Output bit
When C1INV = 0:
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-
When C1INV = 1:
1 = C1 VIN+ < C1 VIN-
0 = C1 VIN+ > C1 VIN-

bit 5 **C2INV**: Comparator 2 Output Inversion bit
1 = C2 output inverted
0 = C2 output not inverted

bit 4 **C1INV**: Comparator 1 Output Inversion bit
1 = C1 output inverted
0 = C1 output not inverted

bit 3 **CIS**: Comparator Input Switch bit
When CM<2:0> = 110:
1 = C1 VIN- connects to RD0/PSP0/C1IN+
C2 VIN- connects to RD2/PSP2/C2IN+
0 = C1 VIN- connects to RD1/PSP1/C1IN-
C2 VIN- connects to RD3/PSP3/C2IN-

bit 2-0 **CM<2:0>**: Comparator Mode bits
Figure 21-1 shows the Comparator modes and the CM<2:0> bit settings.

24.2.4 CAN BAUD RATE REGISTERS

This section describes the CAN Baud Rate registers.

Note:	These registers are writable in Configuration mode only.

REGISTER 24-52: BRGCON1: BAUD RATE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-6 **SJW<1:0>:** Synchronized Jump Width bits

11 = Synchronization jump width time = 4 x TQ
10 = Synchronization jump width time = 3 x TQ
01 = Synchronization jump width time = 2 x TQ
00 = Synchronization jump width time = 1 x TQ

bit 5-0 **BRP<5:0>:** Baud Rate Prescaler bits

111111 = TQ = (2 x 64)/FOSC
111110 = TQ = (2 x 63)/FOSC
:
:
000001 = TQ = (2 x 2)/FOSC
000000 = TQ = (2 x 1)/FOSC

25.5.2 DATA EEPROM CODE PROTECTION

The entire data EEPROM is protected from external reads and writes by two bits: CPD and WRTD. CPD inhibits external reads and writes of data EEPROM. WRTD inhibits internal and external writes to data EEPROM. The CPU can continue to read and write data EEPROM regardless of the protection bit settings.

25.5.3 CONFIGURATION REGISTER PROTECTION

The Configuration registers can be write-protected. The WRTC bit controls protection of the Configuration registers. In normal execution mode, the WRTC bit is readable only. WRTC can only be written via ICSP or an external programmer.

25.6 ID Locations

Eight memory locations (200000h-200007h) are designated as ID locations, where the user can store checksum or other code identification numbers. These locations are both readable and writable during normal execution through the TBLRD and TBLWT instructions or during program/verify. The ID locations can be read when the device is code-protected.

25.7 In-Circuit Serial Programming

PIC18F2480/2580/4480/4580 microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

25.8 In-Circuit Debugger

When the DEBUG Configuration bit is programmed to a '0', the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB® IDE. When the microcontroller has this feature enabled, some resources are not available for general use. Table 25-4 shows which resources are required by the background debugger.

TABLE 25-4: DEBUGGER RESOURCES

I/O pins:	RB6, RB7
Stack:	2 levels

Note: Memory resources listed in MPLAB® IDE.

To use the In-Circuit Debugger function of the microcontroller, the design must implement In-Circuit Serial Programming connections to MCLR/VPP/RE3, VDD, VSS, RB7 and RB6. This will interface to the In-Circuit debugger module available from Microchip or one of the third party development tool companies.

25.9 Single-Supply ICSP Programming

The LVP Configuration bit enables Single-Supply ICSP Programming (formerly known as *Low-Voltage ICSP Programming* or *LVP*). When Single-Supply Programming is enabled, the microcontroller can be programmed without requiring high voltage being applied to the MCLR/VPP/RE3 pin, but the RB5/KBI1/PGM pin is then dedicated to controlling Program mode entry and is not available as a general purpose I/O pin.

While programming using Single-Supply Programming, VDD is applied to the MCLR/VPP/RE3 pin as in normal execution mode. To enter Programming mode, VDD is applied to the PGM pin.

Note 1: High-voltage programming is always available, regardless of the state of the LVP bit, by applying VIHH to the MCLR pin.

2: While in Low-Voltage ICSP Programming mode, the RB5 pin can no longer be used as a general purpose I/O pin and should be held low during normal operation.

3: When using Low-Voltage ICSP Programming (LVP) and the pull-ups on PORTB are enabled, bit 5 in the TRISB register must be cleared to disable the pull-up on RB5 and ensure the proper operation of the device.

4: If the device Master Clear is disabled, verify that either of the following is done to ensure proper entry into ICSP mode:

a) disable Low-Voltage Programming (CONFIG4l<2> = 0); or

b) make certain that RB5/PGM is held low during entry into ICSP.

If Single-Supply ICSP Programming mode will not be used, the LVP bit can be cleared. RB5/KBI1/PGM then becomes available as the digital I/O pin, RB5. The LVP bit may be set or cleared only when using standard high-voltage programming (VIHH applied to the MCLR/VPP/RE3 pin). Once LVP has been disabled, only the standard high-voltage programming is available and must be used to program the device.

Memory that is not code-protected can be erased using either a block erase, or erased row by row, then written at any specified VDD. If code-protected memory is to be erased, a block erase is required. If a block erase is to be performed when using Low-Voltage Programming, the device must be supplied with VDD of 4.5V to 5.5V.

27.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

27.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

27.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

27.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

28.2 DC Characteristics: Power-Down and Supply Current PIC18F2480/2580/4480/4580 (Industrial, Extended) PIC18LF2480/2580/4480/4580 (Industrial) (Continued)

PIC18LF2480/2580/4480/4580 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F2480/2580/4480/4580 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Module Differential Currents (ΔIWDT, ΔIBOR, ΔILVD, ΔIOSCB, ΔIAD)						
D022 (ΔIWDT)	**Watchdog Timer**	1.7	7.6	µA	-40°C	VDD = 2.0V	
		2.1	8	µA	+25°C		
		2.6	8.4	µA	+85°C		
		2.2	11.4	µA	-40°C	VDD = 3.0V	
		2.4	12	µA	+25°C		
		2.8	12.6	µA	+85°C		
		2.9	14.3	µA	-40°C	VDD = 5.0V	
		3.1	15	µA	+25°C		
		3.3	15.8	µA	+85°C		
		7.80	19	µA	+125°C		
D022A (ΔIBOR)	**Brown-out Reset**	17	75	µA	-40°C to +85°C	VDD = 3.0V	
		47	92	µA	-40°C to +85°C	VDD = 5.0V	
		30	58	µA	+125°C		
		0	2	µA	-40°C to +85°C		Sleep mode
		0	5	µA	-40°C to +125°C		BOREN<1:0>
D022B (ΔILVD)	**High/Low-Voltage Detect**	14	47	µA	-40°C to +85°C	VDD = 2.0V	
		18	58	µA	-40°C to +85°C	VDD = 3.0V	
		21	69	µA	-40°C to +85°C	VDD = 5.0V	
		19	50	µA	+125°C		
D025 (ΔIOSCB)	**Timer1 Oscillator**	1.0	8	µA	-40°C	VDD = 2.0V	32 kHz on Timer1(4)
		1.1	8	µA	+25°C		
		1.1	8	µA	+85°C		
		1.2	8.2	µA	-40°C	VDD = 3.0V	32 kHz on Timer1(4)
		1.3	8.2	µA	+25°C		
		1.2	8.2	µA	+85°C		
		1.8	10	µA	-40°C	VDD = 5.0V	32 kHz on Timer1(4)
		1.9	10	µA	+25°C		
		1.9	10	µA	+85°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula, Ir = VDD/2REXT (mA), with REXT in kΩ.

4: Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

28.3 DC Characteristics: PIC18F2480/2580/4480/4580 (Industrial) PIC18LF2480/2580/4480/4580 (Industrial) (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended			
Param No.	**Symbol**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**				
D080		I/O Ports	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083		OSC2/CLKO (RC, RCIO, EC, ECIO modes)	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	VOH	**Output High Voltage(3)**				
D090		I/O Ports	VDD – 0.7	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092		OSC2/CLKO (RC, RCIO, EC, ECIO modes)	VDD – 0.7	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
		Capacitive Loading Specs on Output Pins				
D100	COSC2	OSC2 Pin	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101	CIO	All I/O Pins and OSC2 (in RC mode)	—	50	pF	To meet the AC Timing Specifications
D102	CB	SCL, SDA	—	400	pF	I^2C™ Specification

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC® device be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 28-3: HIGH/LOW-VOLTAGE DETECT CHARACTERISTICS

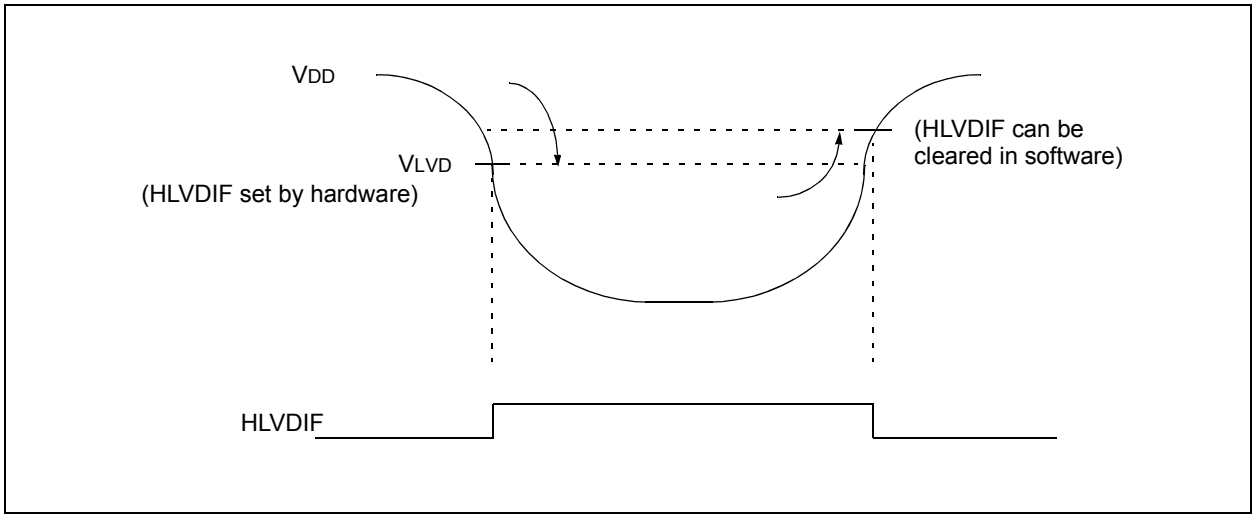


TABLE 28-4: HIGH/LOW-VOLTAGE DETECT CHARACTERISTICS

				Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C < TA < +125°C for extended				
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
D420		HLVD Voltage on VDD Transition High-to-Low	LVV = 0000	2.12	2.17	2.22	V	
			LVV = 0001	2.18	2.23	2.28	V	
			LVV = 0010	2.31	2.36	2.42	V	
			LVV = 0011	2.38	2.44	2.49	V	
			LVV = 0100	2.54	2.60	2.66	V	
			LVV = 0101	2.72	2.79	2.85	V	
			LVV = 0110	2.82	2.89	2.95	V	
			LVV = 0111	3.05	3.12	3.19	V	
			LVV = 1000	3.31	3.39	3.47	V	
			LVV = 1001	3.46	3.55	3.63	V	
			LVV = 1010	3.63	3.71	3.80	V	
			LVV = 1011	3.81	3.90	3.99	V	
			LVV = 1100	4.01	4.11	4.20	V	
			LVV = 1101	4.23	4.33	4.43	V	
			LVV = 1110	4.48	4.59	4.69	V	
			LVV = 1111	1.14	1.2	1.26	V	

TABLE 28-7: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 4.2V TO 5.5V)

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
F10	FOSC	Oscillator Frequency Range	4	—	10	MHz	HS mode only
F11	FSYS	On-Chip VCO System Frequency	16	—	40	MHz	HS mode only
F12	t_{rc}	PLL Start-up Time (lock time)	—	—	2	ms	
F13	ΔCLK	CLKO Stability (jitter)	-2	—	+2	%	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 28-8: AC CHARACTERISTICS: INTERNAL RC ACCURACY
PIC18F2480/2580/4480/4580 (INDUSTRIAL)
PIC18LF2480/2580/4480/4580 (INDUSTRIAL)

PIC18F2480/2580/4480/4580 (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C < TA < +125°C for extended					
Param No.	**Device**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	INTOSC Accuracy @ Freq = 8 MHz, 4 MHz, 2 MHz, 1 MHz, 500 kHz, 250 kHz, 125 kHz(1)						
	PIC18LF2X80/4X80	-2	+/-1	2	%	+25°C	VDD = 2.7-3.3V
		-5	—	5	%	-10°C to +85°C	VDD = 2.7-3.3V
		-10	+/-1	10	%	-40°C to +85°C	VDD = 2.7-3.3V
	PIC18F2X80/4X80	-2	+/-1	2	%	+25°C	VDD = 4.5-5.5V
		-5	—	5	%	-10°C to +85°C	VDD = 4.5-5.5V
		-10	+/-1	10	%	-40°C to +85°C	VDD = 4.5-5.5V
	INTRC Accuracy @ Freq = 31 kHz						
	PIC18LF2X80/4X80	26.562	—	35.938	kHz	-40°C to +85°C	VDD = 2.7-3.3V
	PIC18F2X80/4X80	26.562	—	35.938	kHz	-40°C to +85°C	VDD = 4.5-5.5V

Note 1: Frequency calibrated at 25°C. OSCTUNE register can be used to compensate for temperature drift.

FIGURE 28-14: EXAMPLE SPI SLAVE MODE TIMING (CKE = 0)

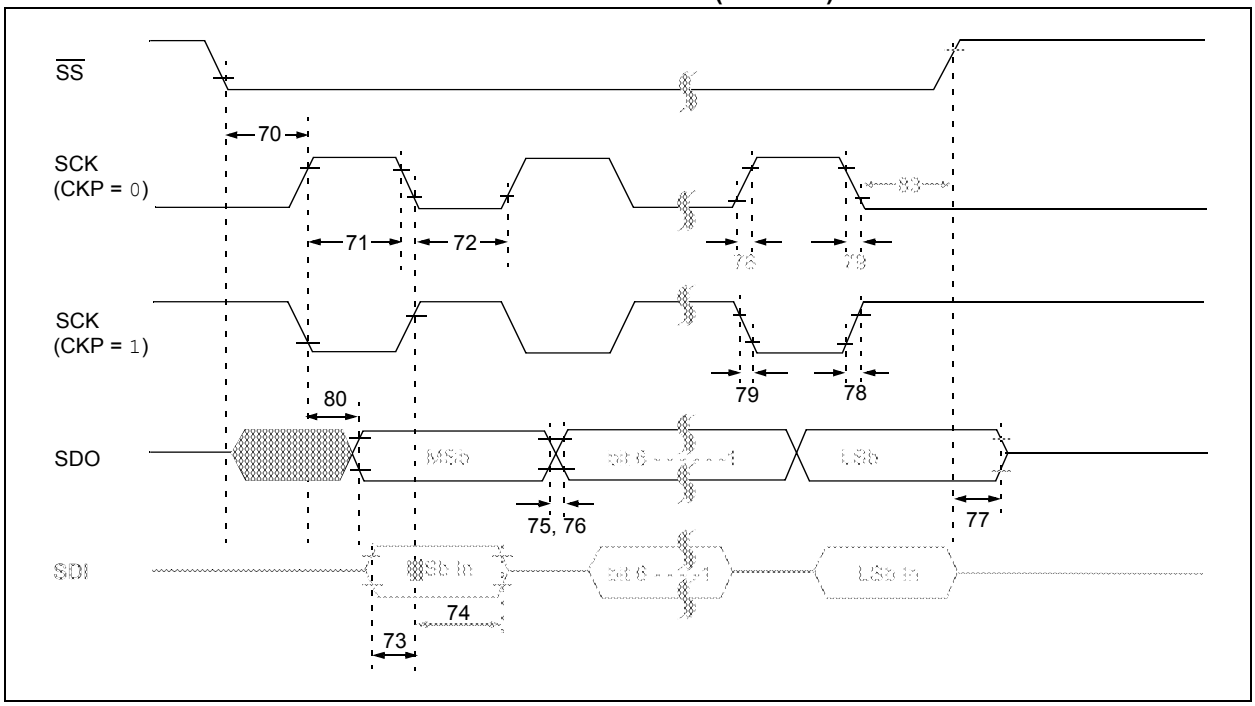


TABLE 28-16: EXAMPLE SPI MODE REQUIREMENTS (SLAVE MODE TIMING, CKE = 0)

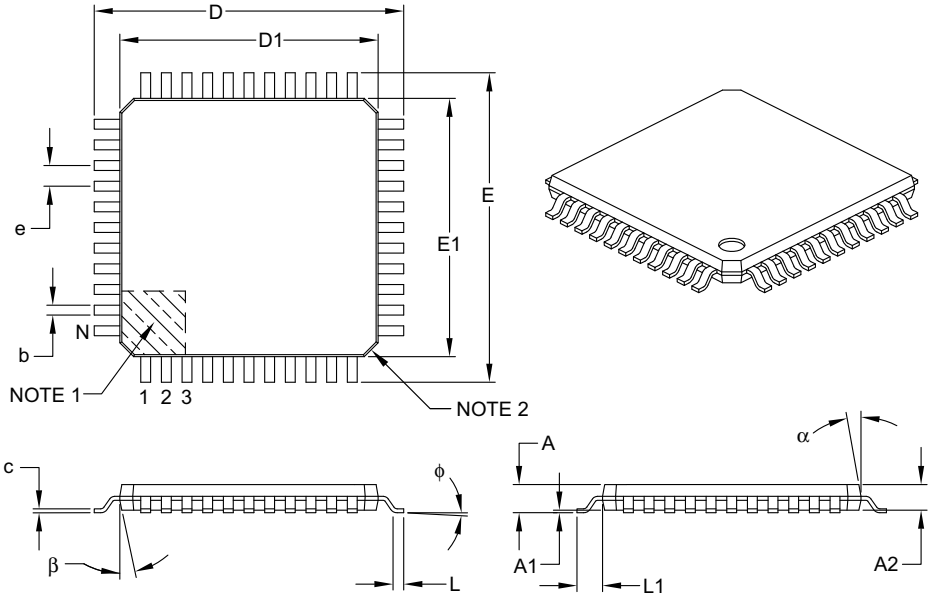
Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SS}$ ↓ to SCK ↓ or SCK ↑ Input		3 Tcy	—	ns	
71	TscH	SCK Input High Time	Continuous	1.25 Tcy + 30	—	ns	
71A			Single Byte	40	—	ns	**(Note 1)**
72	TscL	SCK Input Low Time	Continuous	1.25 Tcy + 30	—	ns	
72A			Single Byte	40	—	ns	**(Note 1)**
73	TdiV2scH, TdiV2scL	Setup Time of SDI Data Input to SCK Edge		20	—	ns	
73A	Tb2b	Last Clock Edge of Byte1 to the First Clock Edge of Byte 2		1.5 Tcy + 40	—	ns	**(Note 2)**
74	TscH2diL, TscL2diL	Hold Time of SDI Data Input to SCK Edge		40	—	ns	
75	TdoR	SDO Data Output Rise Time	PIC18**F**XXXX	—	25	ns	
			PIC18**LF**XXXX		45	ns	VDD = 2.0V
76	TdoF	SDO Data Output Fall Time		—	25	ns	
77	TssH2doZ	$\overline{SS}$ ↑ to SDO Output High-Impedance		10	50	ns	
80	TscH2doV, TscL2doV	SDO Data Output Valid after SCK Edge	PIC18**F**XXXX	—	50	ns	
			PIC18**LF**XXXX		100	ns	VDD = 2.0V
83	TscH2ssH, TscL2ssH	$\overline{SS}$ ↑ after SCK Edge		1.5 Tcy + 40	—	ns	

Note 1: Requires the use of Parameter #73A.

2: Only if Parameter #71A and #72A are used.

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

APPENDIX C: CONVERSION CONSIDERATIONS

This appendix discusses the considerations for converting from previous versions of a device to the ones listed in this data sheet. Typically, these changes are due to the differences in the process technology used. An example of this type of conversion is from a PIC16C74A to a PIC16C74B.

Not Applicable

APPENDIX D: MIGRATION FROM BASELINE TO ENHANCED DEVICES

This section discusses how to migrate from a Baseline device (i.e., PIC16C5X) to an Enhanced MCU device (i.e., PIC18FXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

Not Currently Available